



DST3946DPJ

40V COMPLEMENTARY NPN/PNP SMALL SIGNAL TRANSISTOR IN SOT963

Features

- BV_{CEO} > 40V
- I_C = 200mA Collector Current
- SOT963 Ultra Small Package of 1mm² Footprint
- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

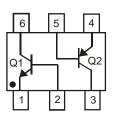
Mechanical Data

- Case: SOT963
- Case Material: Molded Plastic "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads;
 Solderable per MIL-STD-202, Method 208@3
- Weight: 0.0027 grams (Approximate)

SOT963



Top View



Top View Device Schematic and Pin-Out

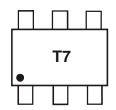
Ordering Information (Note 4)

Product	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DST3946DPJ-7	T7	7	8	10,000
DST3946DPJ-7B	T7	7	8	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/ quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



T7 = Product Type Marking Code



Absolute Maximum Ratings - NPN (Q1) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	60	V
Collector-Emitter Voltage	V_{CEO}	40	V
Emitter-Base Voltage	V_{EBO}	6.0	V
Collector Current	lc	200	mA

Absolute Maximum Ratings - PNP (Q2) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-40	V
Collector-Emitter Voltage	V_{CEO}	-40	V
Emitter-Base Voltage	V_{EBO}	-5.0	V
Collector Current	I _C	-200	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P_{D}	300	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	417	°C/W
Operating and Storage Temperature Range	T_{J} , T_{STG}	-55 to +150	°C

Note: 5. Device mounted on FR-4 PCB with minimum recommended pad layout.

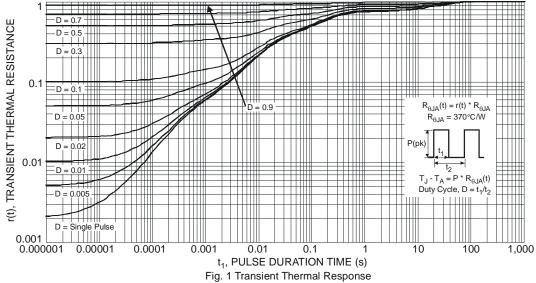
ESD Rating (Note 6)

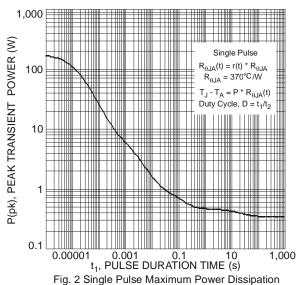
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	200	V	В

Note: 6. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





0.4 P_D, POWER DISSIPATION (W) 1.0 0.0 1.0 60 80 100 120 140 160 T_A, AMBIENT TEMPERATURE (°C)

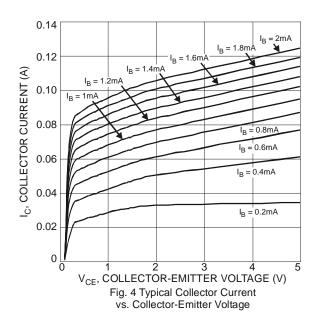
Fig. 3 Power Dissipation vs. Ambient Temperature

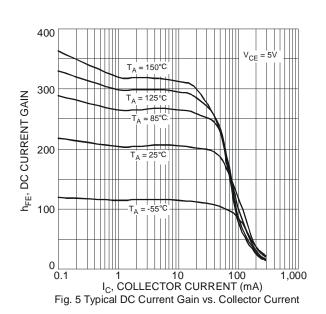


Electrical Characteristics - NPN (Q1) (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)						
Collector-Base Breakdown Voltage	BV_CBO	60		V	$I_C = 10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 7)	BV_CEO	40		V	$I_C = 1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV _{EBO}	6.0	_	V	$I_E = 10\mu A, I_C = 0$	
Collector Cutoff Current	I _{CEX}	_	50	nA	$V_{CE} = 30V$, $V_{EB(OFF)} = 3.0V$	
Base Cutoff Current	I _{BL}	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
ON CHARACTERISTICS (Note 7)						
DC Current Gain	h _{FE}	40 70 100 60 30		_	$\begin{split} & I_C = 100 \mu A, \ V_{CE} = 1.0 V \\ & I_C = 1.0 mA, \ V_{CE} = 1.0 V \\ & I_C = 10 mA, \ V_{CE} = 1.0 V \\ & I_C = 50 mA, \ V_{CE} = 1.0 V \\ & I_C = 100 mA, \ V_{CE} = 1.0 V \end{split}$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	0.20 0.30	V	$I_C = 10$ mA, $I_B = 1.0$ mA $I_C = 50$ mA, $I_B = 5.0$ mA	
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.65	0.85 0.95	V	$I_C = 10\text{mA}, I_B = 1.0\text{mA}$ $I_C = 50\text{mA}, I_B = 5.0\text{mA}$	
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C_OBO	_	4.0	pF	$V_{CB} = 5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	C _{IBO}	_	8.5	pF	$V_{EB} = 0.5V$, $f = 1.0MHz$, $I_{C} = 0$	
Input Impedance	h _{IE}	1.0	10	kΩ		
Voltage Feedback Ratio	h _{RE}	0.5	8.0	x 10 ⁻⁴	$V_{CE} = 10V, I_{C} = 1.0mA,$	
Small Signal Current Gain	h _{FE}	100	400	_	f = 1.0kHz	
Output Admittance	hoE	1.0	40	μs		
Current Gain-Bandwidth Product	f _T	300	_	MHz	V _{CE} = 20V, I _C = 10mA, f = 100MHz	
SWITCHING CHARACTERISTICS						
Delay Time	t _D	_	35	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Rise Time	t _R	_	35	ns	$V_{BE(OFF)} = -0.5V, I_{B1} = 1.0mA$	
Storage Time	ts	_	200	ns	$V_{CC} = 3.0V, I_{C} = 10mA,$	
Fall Time	t _F		50	ns	$I_{B1} = -I_{B2} = 1.0 \text{mA}$	

Note: 7. Short duration pulse test used to minimize self-heating effect.









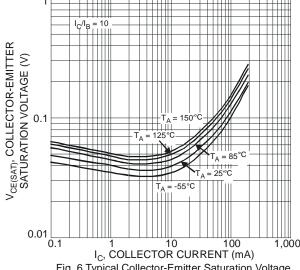
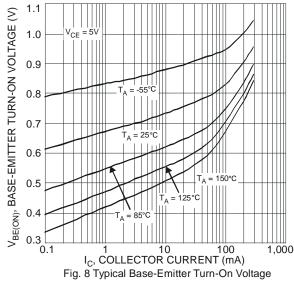
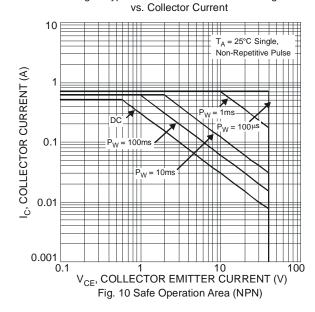


Fig. 6 Typical Collector-Emitter Saturation Voltage vs. Collector Current





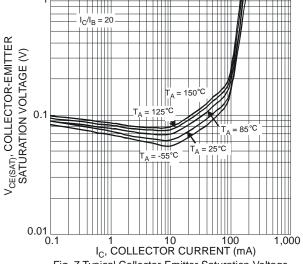


Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Collector Current

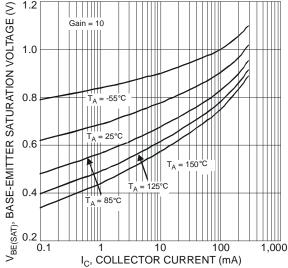


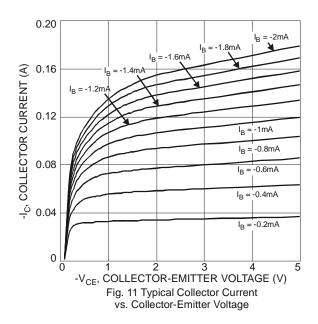
Fig. 9 Typical Base-Emitter Saturation Voltage vs. Collector Current

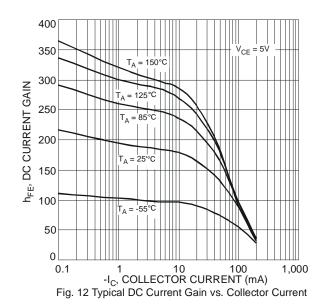


Electrical Characteristics - PNP (Q2) ($@T_A = +25$ °C, unless otherwise specified.)

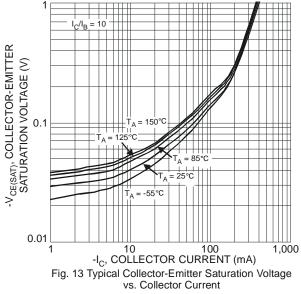
Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS	,					
Collector-Base Breakdown Voltage	BV_{CBO}	-40	_	V	$I_C = -10\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 8)	BV_{CEO}	-40	_	V	$I_C = -1.0 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	BV_{EBO}	-5.0		V	$I_E = -10\mu A, I_C = 0$	
Collector Cutoff Current	I _{CEX}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
Collector Cuton Current	I _{CBO}	_	-50	nA	$V_{CE} = -30V, I_{E} = 0$	
Base Cutoff Current	I_{BL}	_	-50	nA	$V_{CE} = -30V, V_{EB(OFF)} = -3.0V$	
ON CHARACTERISTICS (Note 8)						
		60	_		$I_C = -100\mu A$, $V_{CE} = -1.0V$	
		80	_		$I_C = -1.0 \text{mA}, V_{CE} = -1.0 \text{V}$	
DC Current Gain	h _{FE}	100	300	_	$I_C = -10 \text{mA}, V_{CE} = -1.0 \text{V}$	
		60	_		$I_C = -50 \text{mA}, V_{CE} = -1.0 \text{V}$	
		30	_		$I_C = -100 \text{mA}, V_{CE} = -1.0 \text{V}$	
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		-0.25	V	$I_C = -10mA$, $I_B = -1.0mA$	
Concotor Entities Cuturation Voltage	VCE(SAT)		-0.40	•	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
Base-Emitter Saturation Voltage		-0.65	-0.85	V	$I_C = -10 \text{mA}, I_B = -1.0 \text{mA}$	
		_	-0.95	V	$I_C = -50 \text{mA}, I_B = -5.0 \text{mA}$	
SMALL SIGNAL CHARACTERISTICS				1		
Output Capacitance	C _{OBO}	_	4.5	pF	$V_{CB} = -5.0V$, $f = 1.0MHz$, $I_E = 0$	
Input Capacitance	C _{IBO}	_	10	pF	$V_{EB} = -0.5V$, $f = 1.0MHz$, $I_{C} = 0$	
Input Impedance	h _{IE}	2.0	12	kΩ		
Voltage Feedback Ratio	h_{RE}	0.1	10	x 10 ⁻⁴	$V_{CE} = -10V, I_{C} = -1.0mA,$	
Small Signal Current Gain	h _{FE}	100	400		f = 1.0kHz	
Output Admittance	hOE	3.0	60	μS		
Current Gain-Bandwidth Product	f _T	300	_	MHz	$V_{CE} = -20V, I_{C} = -10mA,$ f = 100MHz	
SWITCHING CHARACTERISTICS						
Delay Time	t _D	_	35	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Rise Time	t _R	_	35	ns	$V_{BE(OFF)} = 0.5V, I_{B1} = -1.0mA$	
Storage Time	ts	_	225	ns	$V_{CC} = -3.0V, I_{C} = -10mA,$	
Fall Time	t _F	_	75	ns	$I_{B1} = -I_{B2} = -1.0$ mA	

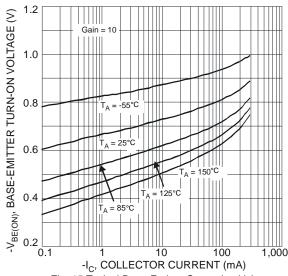
Note: 8. Short duration pulse test used to minimize self-heating effect.

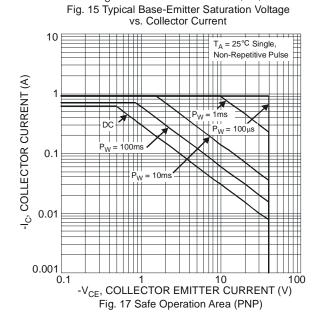


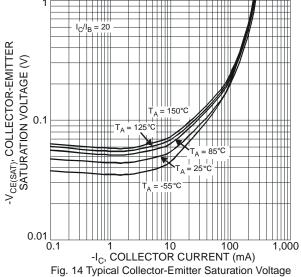












vs. Collector Current

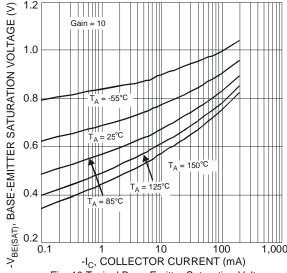


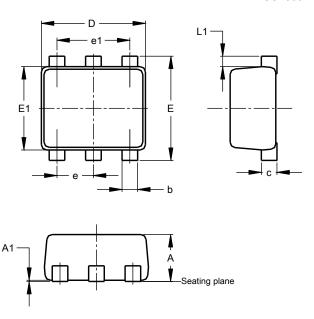
Fig. 16 Typical Base-Emitter Saturation Voltage vs. Collector Current



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT963

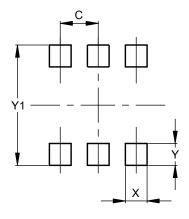


	SOT963					
Dim	Min	Max	Тур			
Α	0.40	0.50	0.45			
A1	0.00	0.05				
b	0.10	0.20	0.15			
C	0.120	0.180	0.150			
ם	0.95	1.05	1.00			
Е	0.95	1.05	1.00			
E1	0.75	0.85	0.80			
е			0.35			
e1			0.70			
L1	0.05	0.15	0.10			
All	All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT963



Dimensions	Value (in mm)		
С	0.350		
Х	0.200		
Υ	0.200		
V1	1 100		



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